



Docket No. 0039-7292-2 DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: KAORI UMEZAWA, ET AL.

GAU: 2814

SERIAL NO: 09/358,388

EXAMINER: MAI, ANH D

CPA FILED: NOVEMBER 20, 2000

FOR: SUBSTRATE HAVING SHALLOW TRENCH ISOLATION AND METHOD OF...

REQUEST FOR CONTINUED EXAMINATION (RCE) TRANSMITTAL

ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

SIR:

This is a request for Continued Examination (RCE) under 37 C.F.R. §1.114 of the above-identified application.

Submission required under 37 C.F.R. §1.114

*Previously Submitted:*

- ☐ Consider the amendment(s)/reply under 37 C.F.R. §1.116 previously filed on
- ☐ Consider the arguments in the Appeal Brief or Reply Brief previously filed on

*Enclosed:*

- ☒ Amendment with Marked-up Copy
- ☐ Information Disclosure Statement (IDS)
- ☒ Other: PETITION FOR EXTENSION OF TIME (1 MONTH)

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APR 23 2002  
TECHNOLOGY CENTER 2300

FEES	RATE	CALCULATIONS
<input type="checkbox"/> Suspension of action on the above-identified application is requested under 37 C.F.R. §1.103(c) for a period of months.	\$130.00	\$0.00
<input checked="" type="checkbox"/> RCE Fee required under 37 C.F.R. §1.17(e)	\$740.00	\$740.00
<input type="checkbox"/>		
<input type="checkbox"/>		\$0.00
TOTAL OF ABOVE CALCULATIONS:		\$740.00
<input type="checkbox"/> REDUCTION BY 50% FOR FILING AS SMALL ENTITY		\$0.00
TOTAL:		\$740.00

- ☒ A check in the amount of **\$850.00** is enclosed

- ☒ Please charge any additional Fees for the papers being filed herewith and for which no check is enclosed herewith, or credit any overpayment to Deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.

- ☒ If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 CFR 1.136, and any additional fees required under 37 CFR 1.136 for any necessary extension of time may be charged to Deposit Account No. 15-0030. A duplicate of this sheet is enclosed.



22850

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Respectfully Submitted,

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0039-7292-2 DIV



IN THE UNITED STATES PATENT & TRADEMARK OFFICE

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IN RE APPLICATION OF:

:

KAORI UMEZAWA ET AL.

: GROUP ART UNIT : 2814

SERIAL NO: 09/358,388

:

CPA FILED: NOVEMBER 20, 2000

: EXAMINER: MAI

FOR: SUBSTRATE HAVING SHALLOW  
TRENCH ISOLATION AND  
METHOD OF MANUFACTURING  
THE SAME

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AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

SIR:

Responsive to the Official Action mailed July 18, 2001, please amend the above-identified application as follows:

IN THE CLAIMS

Please cancel Claim 47 without prejudice or disclaimer.

Please amend claims 9, 10, 25-29, 36, and 45 as shown in the attached marked-up copy to read as follows:

9. (Four times amended) A method of manufacturing a semiconductor substrate having shallow trench isolation regions and a device region sandwiched by the shallow trench isolation regions, comprising:

(a) forming a plurality of grooves on part of a surface of the semiconductor substrate, each of grooves having a width narrower than  $0.5\mu\text{m}$ ;